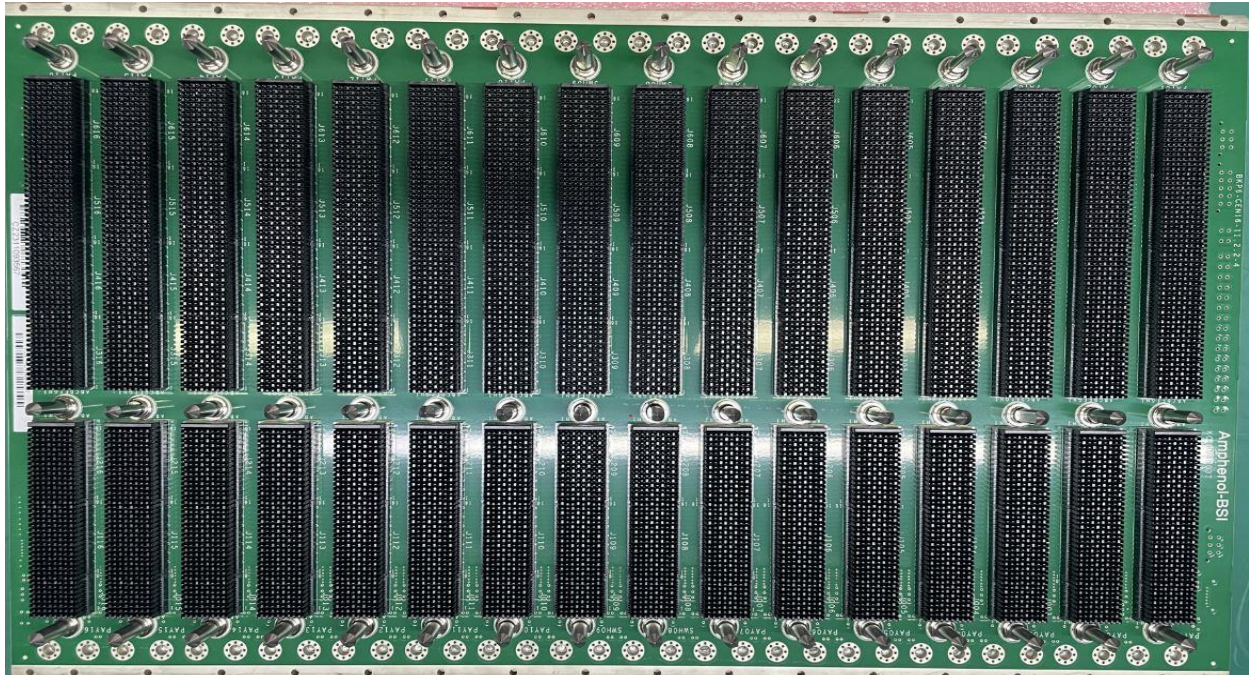


Amphenol Backplane Assembly & System Integration

Amphenol-BSI have been designing, assembling, and testing backplanes for more than 30 years. Our experience of backplane design, manufacturing, development, and electrical test technologies allows us to deliver the highest performance backplane at a product cost you can bring to the market. As part of the Amphenol Corporation, we continue to invest in our technologies to ensure we remain positioned as the most extensively tooled Backplane Supplier in the industry.



Viewed from the front side.

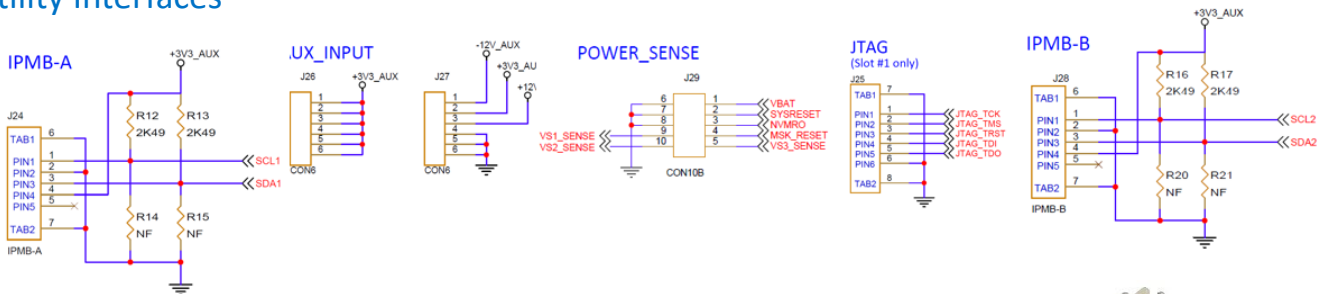
Power Delivery

- 32x Ground locations
- 2x Safety Ground locations
- 9x 5V locations
- 18x 12V locations



| PEM Broaching Standoff | |
|-------------------------|--------------|
| Thread size x Pitch | M3 x 0.5 |
| Height from PCB surface | 4mm ±0.13 |
| Material | Carbon Steel |
| Current rating | 25A |

Utility Interfaces



Molex Micro-Fit 3.0 vertical header
Maximum per contact = 8.5A



Amphenol 1.25mm wire-to-board



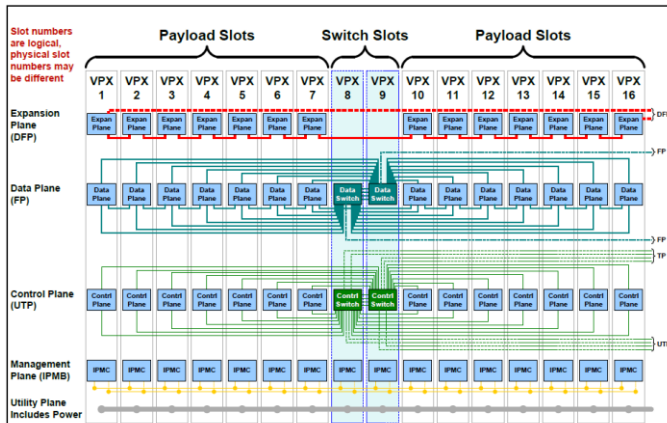


Figure 11.2.2-1 Topology of BKP6-CEN16-11.2.2-n

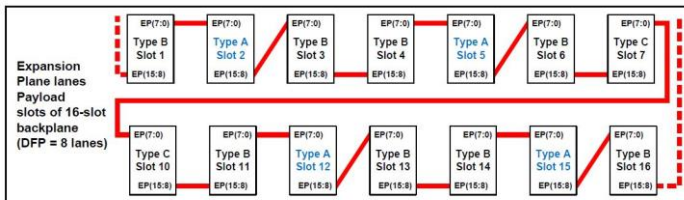
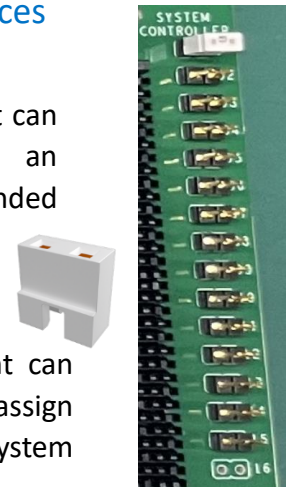


Figure 11.2.2-2 Expansion Plane Lanes of BKP6-CEN16-11.2.2-n

- Data Plane signals are not available on RTMs due to high data rates.
- Control Plane signals are not available on RTMs due to high data rates.
- Management Plane signals are available on RTMs.
- Utility Plane signals are available on RTMs.
- JTAG (J25) access is to VPX 1st slot only.

Configurable Interfaces

- NVMRO
The supplied shunt can be assembled in an open or grounded position.
- System Controller
The supplied shunt can be assembled to assign any slot as the system controller.



General Information

- ANSI/VITA 46.0-2019 VPX Baseline Standard
- ANSI/VITA 65.0-2019 OpenVPX System Standard
- ANSI/VITA 68.1-2019 VPX Compliance Channel
- 2x Switch Slot SLT6-SWH-20U19F-10.4.1
- 14x Payload Slots SLT6-PAY-4F1Q2U2T-10.2.1
- Optional RTM assembly
- Dimension: 426.72mm X 262.05mm X 5.40mm
- Multiple utility connectors for signal access
- Multiple power locations for distributed delivery
- Optimised for high-speed signal performance.
- Edge plating to minimise EMI emissions.

Ordering Information

| Backplane Profile Name | Mechanical | | Channel Data Rate (Gb/s) | | | Ordering Part Number |
|------------------------|------------|-----|--------------------------|---------------|------------|----------------------|
| | Pitch | RTM | Expansion Plane | Control Plane | Data Plane | |
| BKP6-CEN16-11.2.2-4 | 1.0" | yes | 8.0000 | 1.25 | 10.3125 | KC10060037 |

Contact

MARKETING

Martin Walsh
 Martin.walsh@amphenol-tcs.com
 +35-3863871768

ENGINEERING

Mayank Anand
 Mayank.Anand@amphenol-fci.com
 +91-7903580813